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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	85
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	31K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30833fjfp-u3

1.4 Product Information

Table 1.3 lists the product information. Figure 1.2 shows the product numbering system.

Table 1.3 M32C/83 Group (1) (M32C/83)

As of January, 2006

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30835FJGP	PLQP0144KA-A (144P6Q-A)	512K	31K	Flash Memory
M30833FJGP	PLQP0100KB-A (100P6Q-A)			
M30833FJFP	PRQP0100JB-A (100P6S-A)			

Table 1.3 M32C/83 Group (2) (T Version, M32C/83T)

As of January, 2006

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30833FJTGP	PLQP0100KB-A (100P6Q-A)	512K	31K	Flash Memory T Version (High-reliability 85°C Version)

Please contact our sales office for V version information.

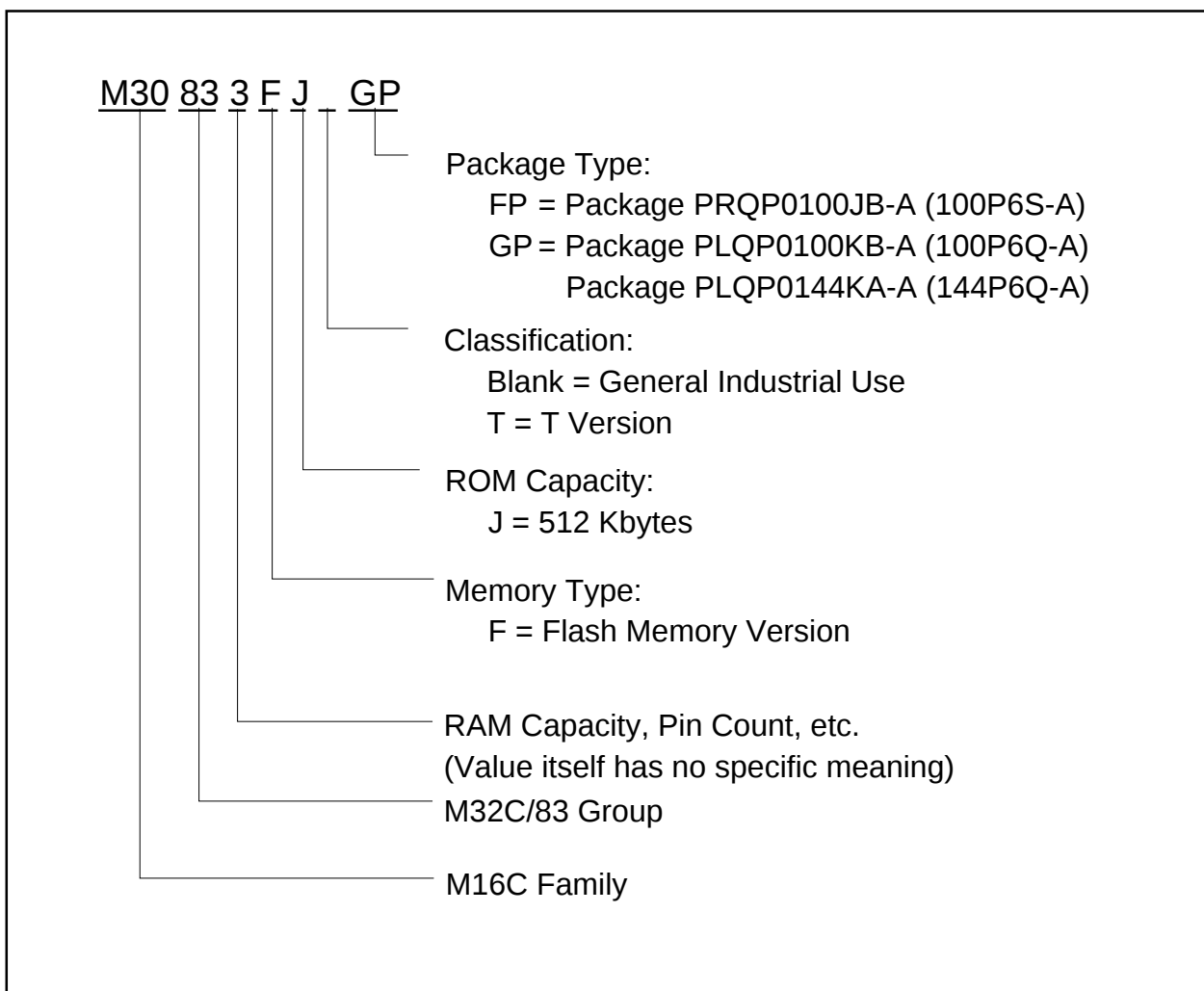


Figure 1.2 Product Numbering System

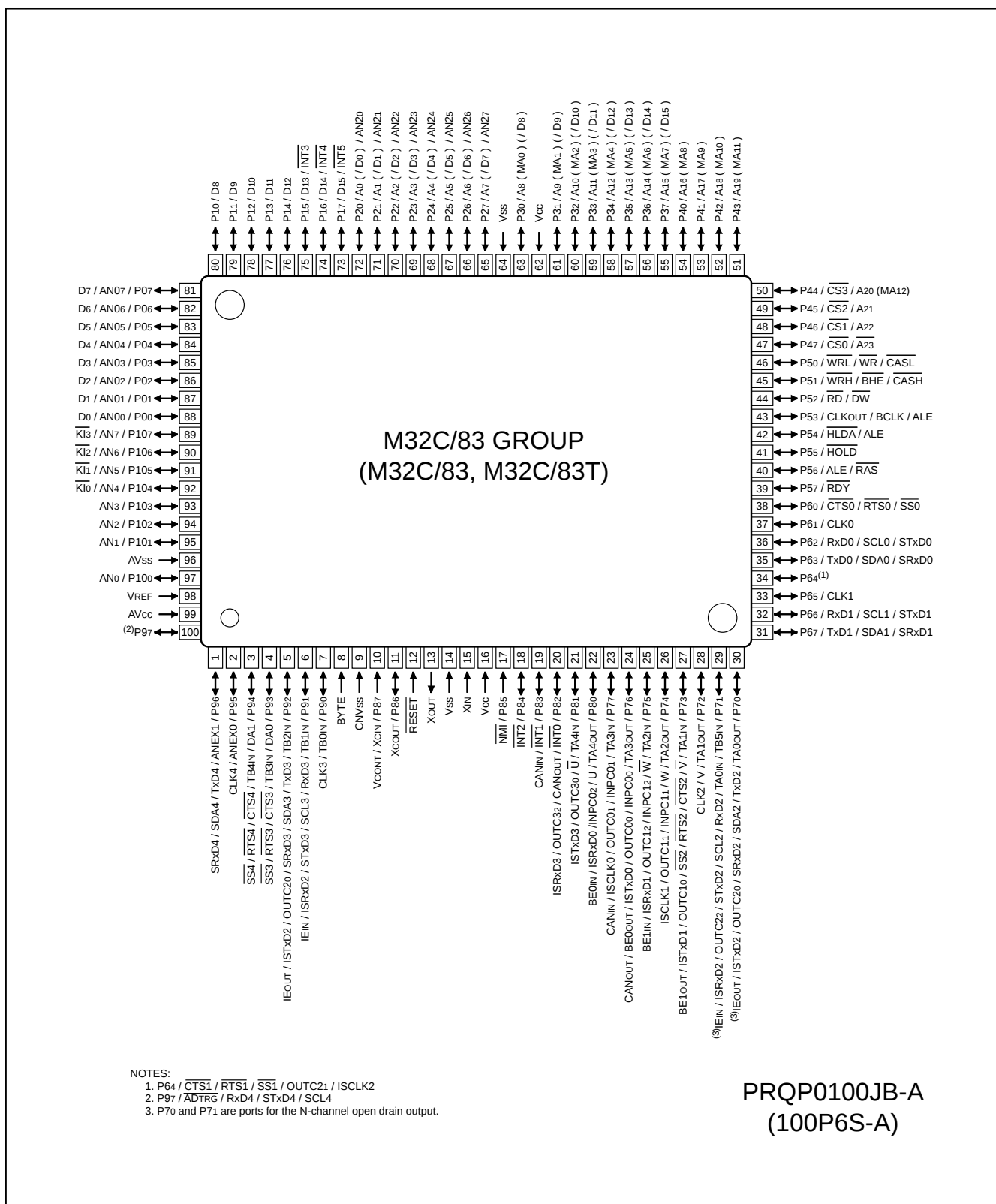


Figure 1.4 Pin Assignment for 100-Pin Package

1.6 Pin Description

Table 1.6 Pin Description (100-Pin and 144-Pin Packages)

Classification	Symbol	I/O Type	Function
Power Supply	Vcc Vss	I	Apply 3.0 to 5.5V to both Vcc pin. Apply 0V to the Vss pin. ⁽¹⁾
Analog Power Supply	AVcc AVss	I	Supplies power to the A/D converter. Connect the AVcc pin to Vcc and the AVss pin to Vss
Reset Input	RESET	I	The microcomputer is in a reset state when "L" is applied to the RESET pin
CNVss	CNVss	I	Switches processor mode. Connect the CNVss pin to Vss to start up in single-chip mode or to Vcc to start up in microprocessor mode
Input to Switch External Data Bus Width ⁽²⁾	BYTE	I	Switches data bus width in external memory space 3. The data bus is 16 bits wide when the BYTE pin is held "L" and 8 bits wide when it is held "H". Set to either. Connect the BYTE pin to Vss to use the microcomputer in single-chip mode
Bus Control Pins ⁽²⁾	D0 to D7	I/O	Inputs and outputs data (D0 to D7) while accessing an external memory space with separate bus
	D8 to D15	I/O	Inputs and outputs data (D8 to D15) while accessing an external memory space with 16-bit separate bus
	A0 to A22	O	Outputs address bits A0 to A22
	A23	O	Outputs inversed address bit A23
	A0/D0 to A7/D7	I/O	Inputs and outputs data (D0 to D7) and outputs 8 low-order address bits (A0 to A7) by time-sharing while accessing an external memory space with multiplexed bus
	A8/D8 to A15/D15	I/O	Inputs and outputs data (D8 to D15) and outputs 8 middle-order address bits (A8 to A15) by time-sharing while accessing an external memory space with 16-bit multiplexed bus
	CS0 to CS3	O	Outputs CS0 to CS3 that are chip-select signals specifying an external space
	WRL / WR WRH / BHE RD	O	Outputs WRL, WRH, (WR, BHE) and RD signals. WRL and WRH can be switched with WR and BHE by program ■ WRL, WRH and RD selected: If external data bus is 16 bits wide, data is written to an even address in external memory space when WRL is held "L". Data is written to an odd address when WRH is held "L". Data is read when RD is held "L". ■ WR, BHE and RD selected: Data is written to external memory space when WR is held "L". Data in an external memory space is read when RD is held "L". An odd address is accessed when BHE is held "L". Select WR, BHE and RD for external 8-bit data bus.
	ALE	O	ALE is a signal latching the address
	HOLD	I	The microcomputer is placed in a hold state while the HOLD pin is held "L"
DRAM Bus Control Pin ⁽²⁾	HLDA	O	Outputs an "L" signal while the microcomputer is placed in a hold state
	RDY	I	Bus is placed in a wait state while the RDY pin is held "L"
	MA0 to MA12	O	When DRAM area is accessed, outputs column and row addresses by time-sharing.
	DW	O	The DW signal becomes "L" when data is written to the DRAM area. CASL and CASH are signals indicating the timing to latch column addresses. The CASL signal becomes "L" when an even address is accessed. The CASH signal becomes "L" when an odd address is accessed. RAS is a signal latching row addresses.
	CASL CASH RAS		

I : Input O : Output I/O : Input and output

NOTES:

1. Apply 4.2 to 5.5V to the Vcc pin when using M32C/83T.
2. Bus control pins in M32C/83T cannot be used.

Address	Register	Symbol	Value after RESET
0030 ₁₆			
0031 ₁₆			
0032 ₁₆			
0033 ₁₆			
0034 ₁₆			
0035 ₁₆			
0036 ₁₆			
0037 ₁₆			
0038 ₁₆			
0039 ₁₆			
003A ₁₆			
003B ₁₆			
003C ₁₆			
003D ₁₆			
003E ₁₆			
003F ₁₆			
0040 ₁₆	DRAM Control Register ⁽¹⁾	DRAMCONT	XX ₁₆
0041 ₁₆	DRAM Refresh Interval Set Register ⁽¹⁾	REFCNT	XX ₁₆
0042 ₁₆			
0043 ₁₆			
0044 ₁₆			
0045 ₁₆			
0046 ₁₆			
0047 ₁₆			
0048 ₁₆			
0049 ₁₆			
004A ₁₆			
004B ₁₆			
004C ₁₆			
004D ₁₆			
004E ₁₆			
004F ₁₆			
0050 ₁₆			
0051 ₁₆			
0052 ₁₆			
0053 ₁₆			
0054 ₁₆			
0055 ₁₆			
0056 ₁₆			
0057 ₁₆	Flash Memory Control Register 0	FMR0	XX00 0001 ₂
0058 ₁₆			
0059 ₁₆			
005A ₁₆			
005B ₁₆			
005C ₁₆			
005D ₁₆			
005E ₁₆			
005F ₁₆			

X: Indeterminate

Blank spaces are reserved. No access is allowed.

NOTES:

1. These registers in M32C/83T cannot be used.

Address	Register	Symbol	Value after RESET
0120 ₁₆	Group 1 Base Timer Register	G1BT	XX ₁₆
0121 ₁₆			XX ₁₆
0122 ₁₆	Group 1 Base Timer Control Register 0	G1BCR0	00 ₁₆
0123 ₁₆	Group 1 Base Timer Control Register 1	G1BCR1	00 ₁₆
0124 ₁₆	Group 1 Time Measurement Prescaler Register 6	G1TPR6	00 ₁₆
0125 ₁₆	Group 1 Time Measurement Prescaler Register 7	G1TPR7	00 ₁₆
0126 ₁₆	Group 1 Function Enable Register	G1FE	00 ₁₆
0127 ₁₆	Group 1 Function Select Register	G1FS	00 ₁₆
0128 ₁₆	Group 1 SI/O Receive Buffer Register	G1RB	XXXX XXXX ₂
0129 ₁₆			XX00 XXXX ₂
012A ₁₆	Group 1 Transmit Buffer/Receive Data Register	G1TB/G1DR	XX ₁₆
012B ₁₆			
012C ₁₆	Group 1 Receive Input Register	G1RI	XX ₁₆
012D ₁₆	Group 1 SI/O Communication Mode Register	G1MR	00 ₁₆
012E ₁₆	Group 1 Transmit Output Register	G1TO	XX ₁₆
012F ₁₆	Group 1 SI/O Communication Control Register	G1CR	0000 X000 ₂
0130 ₁₆	Group 1 Data Compare Register 0	G1CMP0	XX ₁₆
0131 ₁₆	Group 1 Data Compare Register 1	G1CMP1	XX ₁₆
0132 ₁₆	Group 1 Data Compare Register 2	G1CMP2	XX ₁₆
0133 ₁₆	Group 1 Data Compare Register 3	G1CMP3	XX ₁₆
0134 ₁₆	Group 1 Data Mask Register 0	G1MSK0	XX ₁₆
0135 ₁₆	Group 1 Data Mask Register 1	G1MSK1	XX ₁₆
0136 ₁₆			
0137 ₁₆			
0138 ₁₆	Group 1 Receive CRC Code Register	G1RCRC	XX ₁₆
0139 ₁₆			XX ₁₆
013A ₁₆	Group 1 Transmit CRC Code Register	G1TCRC	00 ₁₆
013B ₁₆			00 ₁₆
013C ₁₆	Group 1 SI/O Extended Mode Register	G1EMR	00 ₁₆
013D ₁₆	Group 1 SI/O Extended Receive Control Register	G1ERC	00 ₁₆
013E ₁₆	Group 1 SI/O Special Communication Interrupt Detect Register	G1IRF	0000 00XX ₂
013F ₁₆	Group 1 SI/O Extended Transmit Control Register	G1ETC	0000 0XXX ₂
0140 ₁₆	Group 2 Waveform Generating Register 0	G2PO0	XX ₁₆
0141 ₁₆			XX ₁₆
0142 ₁₆	Group 2 Waveform Generating Register 1	G2PO1	XX ₁₆
0143 ₁₆			XX ₁₆
0144 ₁₆	Group 2 Waveform Generating Register 2	G2PO2	XX ₁₆
0145 ₁₆			XX ₁₆
0146 ₁₆	Group 2 Waveform Generating Register 3	G2PO3	XX ₁₆
0147 ₁₆			XX ₁₆
0148 ₁₆	Group 2 Waveform Generating Register 4	G2PO4	XX ₁₆
0149 ₁₆			XX ₁₆
014A ₁₆	Group 2 Waveform Generating Register 5	G2PO5	XX ₁₆
014B ₁₆			XX ₁₆
014C ₁₆	Group 2 Waveform Generating Register 6	G2PO6	XX ₁₆
014D ₁₆			XX ₁₆
014E ₁₆	Group 2 Waveform Generating Register 7	G2PO7	XX ₁₆
014F ₁₆			XX ₁₆

X: Indeterminate

Blank spaces are reserved. No access is allowed.

Address	Register	Symbol	Value after RESET
0210 ₁₆	CAN0 Slot Interrupt Mask Register	C0SIMKR	00 ₁₆ ⁽²⁾
0211 ₁₆			00 ₁₆ ⁽²⁾
0212 ₁₆			
0213 ₁₆			
0214 ₁₆	CAN0 Error Interrupt Mask Register	C0EIMKR	XXXX X000 ₂ ⁽²⁾
0215 ₁₆	CAN0 Error Interrupt Status Register	C0EISTR	XXXX X000 ₂ ⁽²⁾
0216 ₁₆			
0217 ₁₆	CAN0 Baud Rate Prescaler	C0BRP	0000 0001 ₂ ⁽²⁾
0218 ₁₆			
0219 ₁₆			
021A ₁₆			
021B ₁₆			
021C ₁₆			
021D ₁₆			
021E ₁₆			
021F ₁₆			
0220 ₁₆			
0221 ₁₆			
0222 ₁₆			
0223 ₁₆			
0224 ₁₆			
0225 ₁₆			
0226 ₁₆			
0227 ₁₆			
0228 ₁₆	CAN0 Global Mask Register Standard ID0	C0GMR0	XXX0 0000 ₂ ⁽²⁾
0229 ₁₆	CAN0 Global Mask Register Standard ID1	C0GMR1	XX00 0000 ₂ ⁽²⁾
022A ₁₆	CAN0 Global Mask Register Extended ID0	C0GMR2	XXXX 0000 ₂ ⁽²⁾
022B ₁₆	CAN0 Global Mask Register Extended ID1	C0GMR3	00 ₁₆ ⁽²⁾
022C ₁₆	CAN0 Global Mask Register Extended ID2	C0GMR4	XX00 0000 ₂ ⁽²⁾
022D ₁₆			
022E ₁₆			
022F ₁₆			
0230 ₁₆	CAN0 Message Slot 0 Control Register /	C0MCTL0/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Standard ID0	C0LMAR0	XXX0 0000 ₂ ⁽²⁾
0231 ₁₆	CAN0 Message Slot 1 Control Register /	C0MCTL1/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Standard ID1	C0LMAR1	XX00 0000 ₂ ⁽²⁾
0232 ₁₆	CAN0 Message Slot 2 Control Register /	C0MCTL2/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Extended ID0	C0LMAR2	XXXX 0000 ₂ ⁽²⁾
0233 ₁₆	CAN0 Message Slot 3 Control Register /	C0MCTL3/	00 ₁₆ ⁽²⁾
	CAN0 Local Mask Register A Extended ID1	C0LMAR3	00 ₁₆ ⁽²⁾
0234 ₁₆	CAN0 Message Slot 4 Control Register /	C0MCTL4/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register A Extended ID2	C0LMAR4	XX00 0000 ₂ ⁽²⁾
0235 ₁₆	CAN0 Message Slot 5 Control Register	C0MCTL5	00 ₁₆ ⁽²⁾
0236 ₁₆	CAN0 Message Slot 6 Control Register	C0MCTL6	00 ₁₆ ⁽²⁾
0237 ₁₆	CAN0 Message Slot 7 Control Register	C0MCTL7	00 ₁₆ ⁽²⁾
0238 ₁₆	CAN0 Message Slot 8 Control Register /	C0MCTL8/	0000 0000 ₂ ⁽²⁾
	CAN0 Local Mask Register B Standard ID0	C0LMBR0	XXX0 0000 ₂ ⁽²⁾

(Note 1)

X: Indeterminate

Blank spaces are reserved. No access is allowed.

NOTES:

1. The BANKSEL bit in the C0CTLR1 register switches functions for addresses 0220₁₆ to 023F₁₆.
2. Values are obtained by setting the SLEEP bit in the C0SLPR register to "1" (sleep mode exited) and supplying a clock to the CAN module after reset.

Address	Register	Symbol	Value after RESET
02F0 ₁₆			
02F1 ₁₆			
02F2 ₁₆			
02F3 ₁₆			
02F4 ₁₆	UART4 Special Mode Register 4	U4SMR4	00 ₁₆
02F5 ₁₆	UART4 Special Mode Register 3	U4SMR3	00 ₁₆
02F6 ₁₆	UART4 Special Mode Register 2	U4SMR2	00 ₁₆
02F7 ₁₆	UART4 Special Mode Register	U4SMR	00 ₁₆
02F8 ₁₆	UART4 Transmit/Receive Mode Register	U4MR	00 ₁₆
02F9 ₁₆	UART4 Baud Rate Register	U4BRG	XX ₁₆
02FA ₁₆	UART4 Transmit Buffer Register	U4TB	XX ₁₆
02FB ₁₆			XX ₁₆
02FC ₁₆	UART4 Transmit/Receive Control Register 0	U4C0	0000 1000 ₂
02FD ₁₆	UART4 Transmit/Receive Control Register 1	U4C1	0000 0010 ₂
02FE ₁₆	UART4 Receive Buffer Register	U4RB	XX ₁₆
02FF ₁₆			XX ₁₆
0300 ₁₆	Timer B3, B4, B5 Count Start Flag	TBSR	000X XXXX ₂
0301 ₁₆			
0302 ₁₆	Timer A1-1 Register	TA11	XX ₁₆
0303 ₁₆			XX ₁₆
0304 ₁₆	Timer A2-1 Register	TA21	XX ₁₆
0305 ₁₆			XX ₁₆
0306 ₁₆	Timer A4-1 Register	TA41	XX ₁₆
0307 ₁₆			XX ₁₆
0308 ₁₆	Three-Phase PWM Control Register 0	INVC0	00 ₁₆
0309 ₁₆	Three-Phase PWM Control Register 1	INVC1	00 ₁₆
030A ₁₆	Three-Phase output Buffer Register 0	IDB0	XX11 1111 ₂
030B ₁₆	Three-Phase output Buffer Register 1	IDB1	XX11 1111 ₂
030C ₁₆	Dead Time Timer	DTT	XX ₁₆
030D ₁₆	Timer B2 Interrupt Generating Frequency Set Counter	ICTB2	XX ₁₆
030E ₁₆			
030F ₁₆			
0310 ₁₆	Timer B3 Register	TB3	XX ₁₆
0311 ₁₆			XX ₁₆
0312 ₁₆	Timer B4 Register	TB4	XX ₁₆
0313 ₁₆			XX ₁₆
0314 ₁₆	Timer B5 Register	TB5	XX ₁₆
0315 ₁₆			XX ₁₆
0316 ₁₆			
0317 ₁₆			
0318 ₁₆			
0319 ₁₆			
031A ₁₆			
031B ₁₆	Timer B3 Mode Register	TB3MR	00XX 0000 ₂
031C ₁₆	Timer B4 Mode Register	TB4MR	00XX 0000 ₂
031D ₁₆	Timer B5 Mode Register	TB5MR	00XX 0000 ₂
031E ₁₆			
031F ₁₆	External Interrupt Cause Select Register	IFSR	00 ₁₆

X: Indeterminate

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Address	Register	Symbol	Value after RESET
0380 ₁₆ 0381 ₁₆	A/D0 Register 0	AD00	XX ₁₆ XX ₁₆
0382 ₁₆ 0383 ₁₆	A/D0 Register 1	AD01	XX ₁₆ XX ₁₆
0384 ₁₆ 0385 ₁₆	A/D0 Register 2	AD02	XX ₁₆ XX ₁₆
0386 ₁₆ 0387 ₁₆	A/D0 Register 3	AD03	XX ₁₆ XX ₁₆
0388 ₁₆ 0389 ₁₆	A/D0 Register 4	AD04	XX ₁₆ XX ₁₆
038A ₁₆ 038B ₁₆	A/D0 Register 5	AD05	XX ₁₆ XX ₁₆
038C ₁₆ 038D ₁₆	A/D0 Register 6	AD06	XX ₁₆ XX ₁₆
038E ₁₆ 038F ₁₆	A/D0 Register 7	AD07	XX ₁₆ XX ₁₆
0390 ₁₆			
0391 ₁₆			
0392 ₁₆			
0393 ₁₆			
0394 ₁₆ 0395 ₁₆	A/D0 Control Register 2	AD0CON2	X000 0000 ₂
0396 ₁₆	A/D0 Control Register 0	AD0CON0	00 ₁₆
0397 ₁₆	A/D0 Control Register 1	AD0CON1	00 ₁₆
0398 ₁₆ 0399 ₁₆	D/A Register 0	DA0	XX ₁₆
039A ₁₆ 039B ₁₆	D/A Register 1	DA1	XX ₁₆
039C ₁₆ 039D ₁₆	D/A Control Register	DACON	XXXX XX00 ₂
039E ₁₆			
039F ₁₆			

X: Indeterminate

Blank spaces are reserved. No access is allowed.

**Table 5.4 A/D Conversion Characteristics (V_{CC} = AV_{CC} = V_{REF} = 4.2 to 5.5V, V_{SS} = AV_{SS} = 0V
at Topr = -20 to 85°C, f(X_{IN}) = 32MHz unless otherwise specified)**

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min	Typ	Max	
-	Resolution	V _{REF} =V _{CC}			10	Bits
INL	Integral Nonlinearity Error	V _{REF} =V _{CC} =5V			±3	LSB
						LSB
					±7	LSB
						LSB
DNL	Differential Nonlinearity Error				±1	LSB
-	Offset Error				±3	LSB
-	Gain Error				±3	LSB
R _{LADDER}	Resistor Ladder	V _{REF} =V _{CC}	8		40	kΩ
t _{CONV}	10-bit Conversion Time		2.1			μs
t _{CONV}	8-bit Conversion Time		1.8			μs
t _{SAMP}	Sample Time		0.2			μs
V _{REF}	Reference Voltage		2		V _{CC}	V
V _{IA}	Analog Input Voltage		0		V _{REF}	V

NOTES:

1. Divide f(X_{IN}), if exceeding 16 MHz, to keep φ_{AD} frequency at 16 MHz or less.

**Table 5.5 D/A Conversion Characteristics (V_{CC} = V_{REF} = 4.2 to 5.5V, V_{SS} = AV_{SS} = 0V
at Topr = -20 to 85°C, f(X_{IN}) = 32MHz unless otherwise specified)**

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min	Typ	Max	
-	Resolution				8	Bits
-	Absolute Accuracy				1.0	%
t _{SU}	Setup Time				3	μs
R _O	Output Resistance		4	10	20	kΩ
I _{VREF}	Reference Power Supply Input Current	(Note 1)			1.5	mA

NOTES:

1. Measurement results when using one D/A converter. The DAI register (i=0, 1) of the D/A converter not being used is set to "0016". The resistor ladder in the A/D converter is excluded. I_{VREF} flows even if the VCUT bit in the ADiCON1 register is set to "0" (no V_{REF} connection).

Table 5.6 Flash Memory Version Electrical Characteristics

Parameter	Standard			Unit
	Min	Typ	Max	
Program Time (per page)		8	120	ms
Block Erase Time (per block)		50	600	ms

NOTES:

1. V_{CC}= 4.2 to 5.5V (through VDC), 3.0 to 3.6V (not through VDC) at Topr= 0 to 60° C, unless otherwise specified

Timing Requirements**(V_{CC} = 4.2 to 5.5V, V_{SS} = 0V at Topr = –20 to 85°C unless otherwise specified)****Table 5.9 Timer A Input (Count Source Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min	Max	
t _{C(TA)}	TA _{IN} Input Cycle Time	100		ns
t _{W(TAH)}	TA _{IN} Input High ("H") Pulse Width	40		ns
t _{W(TAL)}	TA _{IN} Input Low ("L") Pulse Width	40		ns

Table 5.10 Timer A Input (Gate Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
t _{C(TA)}	TA _{IN} Input Cycle Time	400		ns
t _{W(TAH)}	TA _{IN} Input High ("H") Pulse Width	200		ns
t _{W(TAL)}	TA _{IN} Input Low ("L") Pulse Width	200		ns

Table 5.11 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
t _{C(TA)}	TA _{IN} Input Cycle Time	200		ns
t _{W(TAH)}	TA _{IN} Input High ("H") Pulse Width	100		ns
t _{W(TAL)}	TA _{IN} Input Low ("L") Pulse Width	100		ns

Table 5.12 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
t _{W(TAH)}	TA _{IN} Input High ("H") Pulse Width	100		ns
t _{W(TAL)}	TA _{IN} Input Low ("L") Pulse Width	100		ns

Table 5.13 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
t _{C(UP)}	TA _{IOU} Input Cycle Time	2000		ns
t _{W(UPH)}	TA _{IOU} Input High ("H") Pulse Width	1000		ns
t _{W(UPL)}	TA _{IOU} Input Low ("L") Pulse Width	1000		ns
t _{SU(UP-TIN)}	TA _{IOU} Input Setup Time	400		ns
t _{H(TIN-UP)}	TA _{IOU} Input Hold Time	400		ns

Switching Characteristics(V_{CC} = 4.2 to 5.5V, V_{SS} = 0V at Topr = –20 to 85°C unless otherwise specified)**Table 5.22 Memory Expansion Mode and Microprocessor Mode
(With a Wait State, Accessing an External Memory and Selecting a Space with the Multiplexed Bus)**

Symbol	Parameter	Measurement Condition	Standard		Unit
			Min	Max	
td(BCLK-AD)	Address Output Delay Time	See Figure 5.1		18	ns
th(BCLK-AD)	Address Output Hold Time (BCLK standard)		-3		ns
th(RD-AD)	Address Output Hold Time (RD standard)		(Note 1)		ns
th(WR-AD)	Address Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-CS)	Chip-select Signal Output Delay Time			18	ns
th(BCLK-CS)	Chip-select Signal Output Hold Time (BCLK standard)		-3		ns
th(RD-CS)	Chip-select Signal Output Hold Time (RD standard)		(Note 1)		ns
th(WR-CS)	Chip-select Signal Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-RD)	RD Signal Output Delay Time			18	ns
th(BCLK-AD)	RD Signal Output Hold Time		-5		ns
td(BCLK-WR)	WR Signal Output Delay Time			18	ns
th(BCLK-WR)	WR Signal Output Hold Time		-3		ns
td(DB-WR)	Data Output Delay Time (WR standard)		(Note 1)		ns
th(WR-DB)	Data Output Hold Time (WR standard)		(Note 1)		ns
td(BCLK-ALE)	ALE Signal Output Delay Time (BCLK standard)			18	ns
th(BCLK-ALE)	ALE Signal Output Hold Time (BCLK standard)		-2		ns
td(AD-ALE)	ALE Signal Output Delay Time (address standard)		(Note 1)		ns
th(ALE-AD)	ALE Signal Output Hold Time (address standard)		(Note 1)		ns
tdZ(RD-AD)	Address Output High-Impedance Time			8	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency.

$$th(RD - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(WR - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$th(RD - CS) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

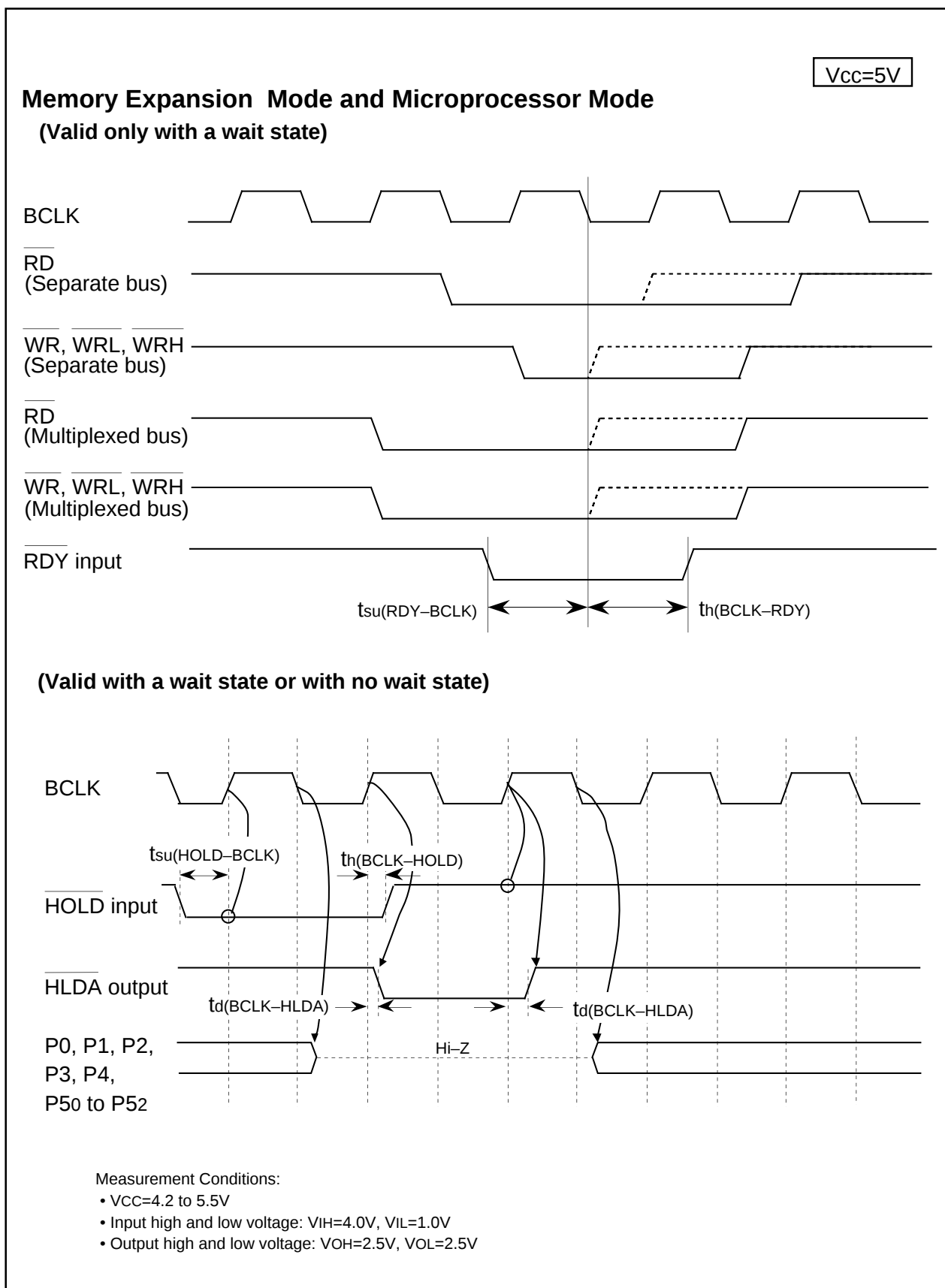
$$th(WR - CS) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$td(DB - WR) = \frac{10^9 \times m}{f(BCLK) \times 2} - 25 \quad [ns] \quad (m=3 \text{ with 2 wait states and } m=5 \text{ with 3 wait states})$$

$$th(WR - DB) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

$$td(AD - ALE) = \frac{10^9}{f(BCLK) \times 2} - 20 \quad [ns]$$

$$th(ALE - AD) = \frac{10^9}{f(BCLK) \times 2} - 10 \quad [ns]$$

Figure 5.9 V_{CC}=5V Timing Diagram (8)

Timing Requirements (V_{CC} = 3.0 to 3.6V, V_{SS} = 0V at T_{opr} = –20 to 85°C unless otherwise specified)**Table 5.28 External Clock Input**

Symbol	Parameter	Standard		Unit
		Min	Max	
t _c	External Clock Input Cycle Time	50		ns
t _{W(H)}	External Clock Input High ("H") Pulse Width	22		ns
t _{W(L)}	External Clock Input Low ("L") Pulse Width	22		ns
t _r	External Clock Rise Time		5	ns
t _f	External Clock Fall Time		5	ns

Table 5.29 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min	Max	
t _{ac1(RD-DB)}	Data Input Access Time (RD standard, with no wait state)		(Note 1)	ns
t _{ac1(AD-DB)}	Data Input Access Time (AD standard, CS standard, with no wait state)		(Note 1)	ns
t _{ac2(RD-DB)}	Data Input Access Time (RD standard, with a wait state)		(Note 1)	ns
t _{ac2(AD-DB)}	Data Input Access Time (AD standard, CS standard, with a wait state)		(Note 1)	ns
t _{ac3(RD-DB)}	Data Input Access Time (RD standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
t _{ac3(AD-DB)}	Data Input Access Time (AD standard, CS standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
t _{ac4(RAS-DB)}	Data Input Access Time (RAS standard, when accessing a DRAM space)		(Note 1)	ns
t _{ac4(CAS-DB)}	Data Input Access Time (CAS standard, when accessing a DRAM space)		(Note 1)	ns
t _{ac4(CAD-DB)}	Data Input Access Time (CAD standard, when accessing a DRAM space)		(Note 1)	ns
t _{SU(DB-BCLK)}	Data Input Setup Time	30		ns
t _{SU(RDY-BCLK)}	RDY Input Setup Time	40		ns
t _{SU(HOLD-BCLK)}	HOLD Input Setup Time	60		ns
t _{H(RD-DB)}	Data Input Hold Time	0		ns
t _{H(CAS-DB)}	Data Input Hold Time	0		ns
t _{H(BCLK-RDY)}	RDY Input Hold Time	0		ns
t _{H(BCLK-HOLD)}	HOLD Input Hold Time	0		ns
t _{d(BCLK-HLDA)}	HLDA Output Delay Time		25	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency. Insert a wait state or lower operation frequency, f_(BCLK), if the calculated value is negative.

$$t_{ac1(RD-DB)} = \frac{10^9}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}]$$

$$t_{ac1(AD-DB)} = \frac{10^9}{f_{(BCLK)}} - 35 \quad [\text{ns}]$$

$$t_{ac2(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \quad (m=3 \text{ with 1 wait state, } m=5 \text{ with 2 wait states and } m=7 \text{ with 3 wait states})$$

$$t_{ac2(AD-DB)} = \frac{10^9 \times n}{f_{(BCLK)}} - 35 \quad [\text{ns}] \quad (n=2 \text{ with 1 wait state, } n=3 \text{ with 2 wait states and } n=4 \text{ with 3 wait states})$$

$$t_{ac3(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \quad (m=3 \text{ with 2 wait states and } m=5 \text{ with 3 wait states})$$

$$t_{ac3(AD-DB)} = \frac{10^9 \times n}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \quad (n=5 \text{ with 2 wait states and } n=7 \text{ with 3 wait states})$$

$$t_{ac4(RAS-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \quad (m=3 \text{ with 1 wait state and } m=5 \text{ with 2 wait states})$$

$$t_{ac4(CAS-DB)} = \frac{10^9 \times n}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \quad (n=1 \text{ with 1 wait state and } n=3 \text{ with 2 wait states})$$

$$t_{ac4(CAD-DB)} = \frac{10^9 \times l}{f_{(BCLK)}} - 35 \quad [\text{ns}] \quad (l=1 \text{ with 1 wait state and } l=2 \text{ with 2 wait states})$$

Timing Requirements**(V_{CC} = 3.0 to 3.6V, V_{SS} = 0V at Topr = –20 to 85°C unless otherwise specified)****Table 5.30 Timer A Input (Count Source Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TA _{IN} Input Cycle Time	100		ns
tw(TAH)	TA _{IN} Input High ("H") Pulse Width	40		ns
tw(TAL)	TA _{IN} Input Low ("L") Pulse Width	40		ns

Table 5.31 Timer A Input (Gate Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TA _{IN} Input Cycle Time	400		ns
tw(TAH)	TA _{IN} Input High ("H") Pulse Width	200		ns
tw(TAL)	TA _{IN} Input Low ("L") Pulse Width	200		ns

Table 5.32 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TA _{IN} Input Cycle Time	200		ns
tw(TAH)	TA _{IN} Input High ("H") Pulse Width	100		ns
tw(TAL)	TA _{IN} Input Low ("L") Pulse Width	100		ns

Table 5.33 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tw(TAH)	TA _{IN} Input High ("H") Pulse Width	100		ns
tw(TAL)	TA _{IN} Input Low ("L") Pulse Width	100		ns

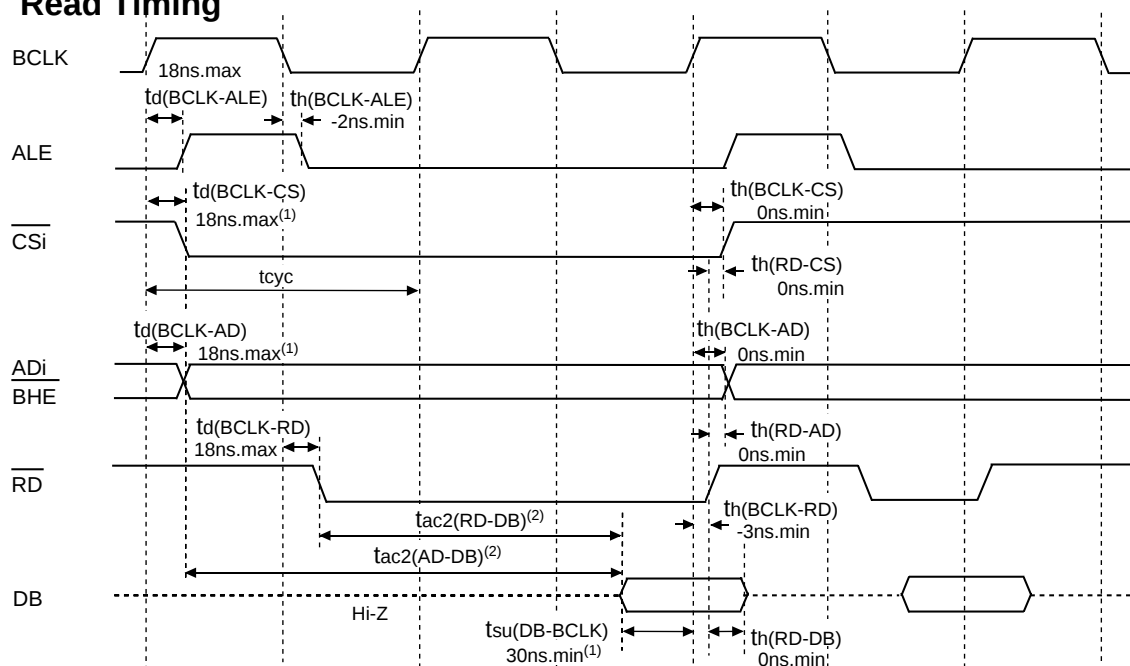
Table 5.34 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(UP)	TA _{IOUT} Input Cycle Time	2000		ns
tw(UPH)	TA _{IOUT} Input High ("H") Pulse Width	1000		ns
tw(UPL)	TA _{IOUT} Input Low ("L") Pulse Width	1000		ns
tsu(UP-TIN)	TA _{IOUT} Input Setup Time	400		ns
th(TIN-UP)	TA _{IOUT} Input Hold Time	400		ns

V_{CC}=3.3V

Memory Expansion Mode and Microprocessor Mode (with a wait state)

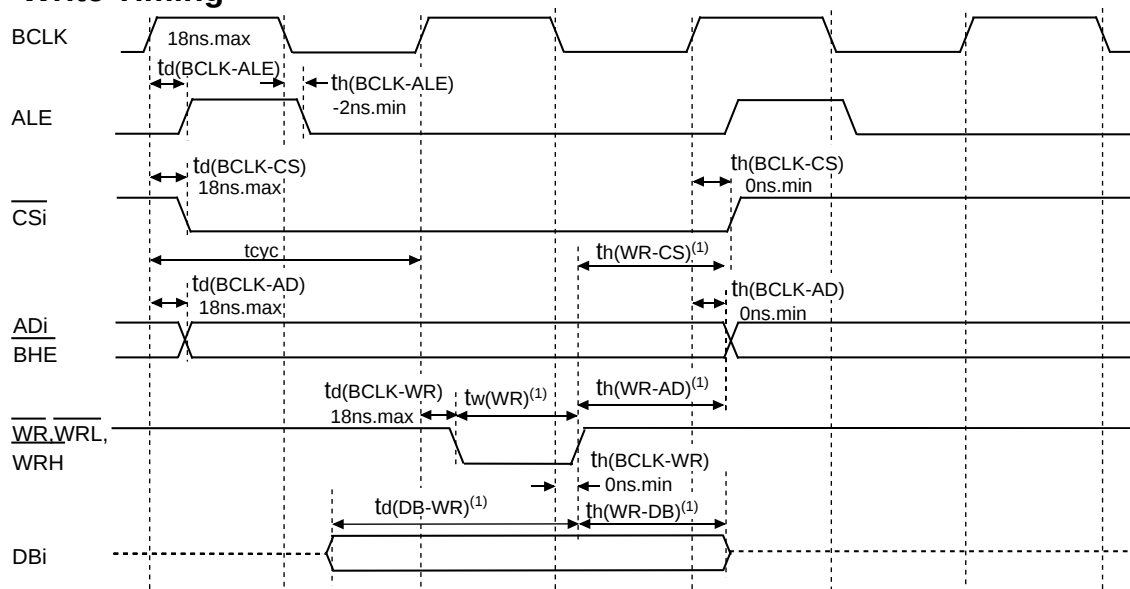
Read Timing



NOTES:

- Values guaranteed only when the microcomputer is used independently. A maximum of 35ns is guaranteed for $t_d(\text{BCLK-AD}) + t_{su}(\text{DB-BCLK})$.
- Varies with operation frequency.
 $t_{ac2}(\text{RD-DB}) = (t_{cyc}/2 \times m - 35)\text{ns.max}$ ($m=3$ with 1 wait state, $m=5$ with 2 wait states and $m=7$ with 3 wait states)
 $t_{ac2}(\text{AD-DB}) = (t_{cyc} \times n - 35)\text{ns.max}$ ($n=2$ with 1 wait state, $n=3$ with 2 wait states and $n=4$ with 3 wait states)

Write Timing



NOTES:

- Varies with operation frequency.
 $t_d(\text{DB-WR}) = (t_{cyc} \times n - 20)\text{ns.min}$ ($n=1$ with 1 wait state, $n=2$ with 2 wait states and $n=3$ with 3 wait states)
 $t_h(\text{WR-DB}) = (t_{cyc}/2 - 10)\text{ns.min}$
 $t_h(\text{WR-AD}) = (t_{cyc}/2 - 10)\text{ns.min}$
 $t_h(\text{WR-CS}) = (t_{cyc}/2 - 10)\text{ns.min}$
 $t_w(\text{WR}) = (t_{cyc}/2 \times n - 15)\text{ns.min}$ ($n=1$ with 1 wait state, $n=3$ with 2 wait states and $n=5$ with 3 wait states)

Measurement Conditions:

- V_{CC}=3.0 to 3.6V
- Input high and low voltage:
V_{IH}=1.5V, V_{IL}=0.5V
- Output high and low voltage:
V_{OH}=1.5V, V_{OL}=1.5V

Figure 5.11 V_{CC}=3.3V Timing Diagram (2)

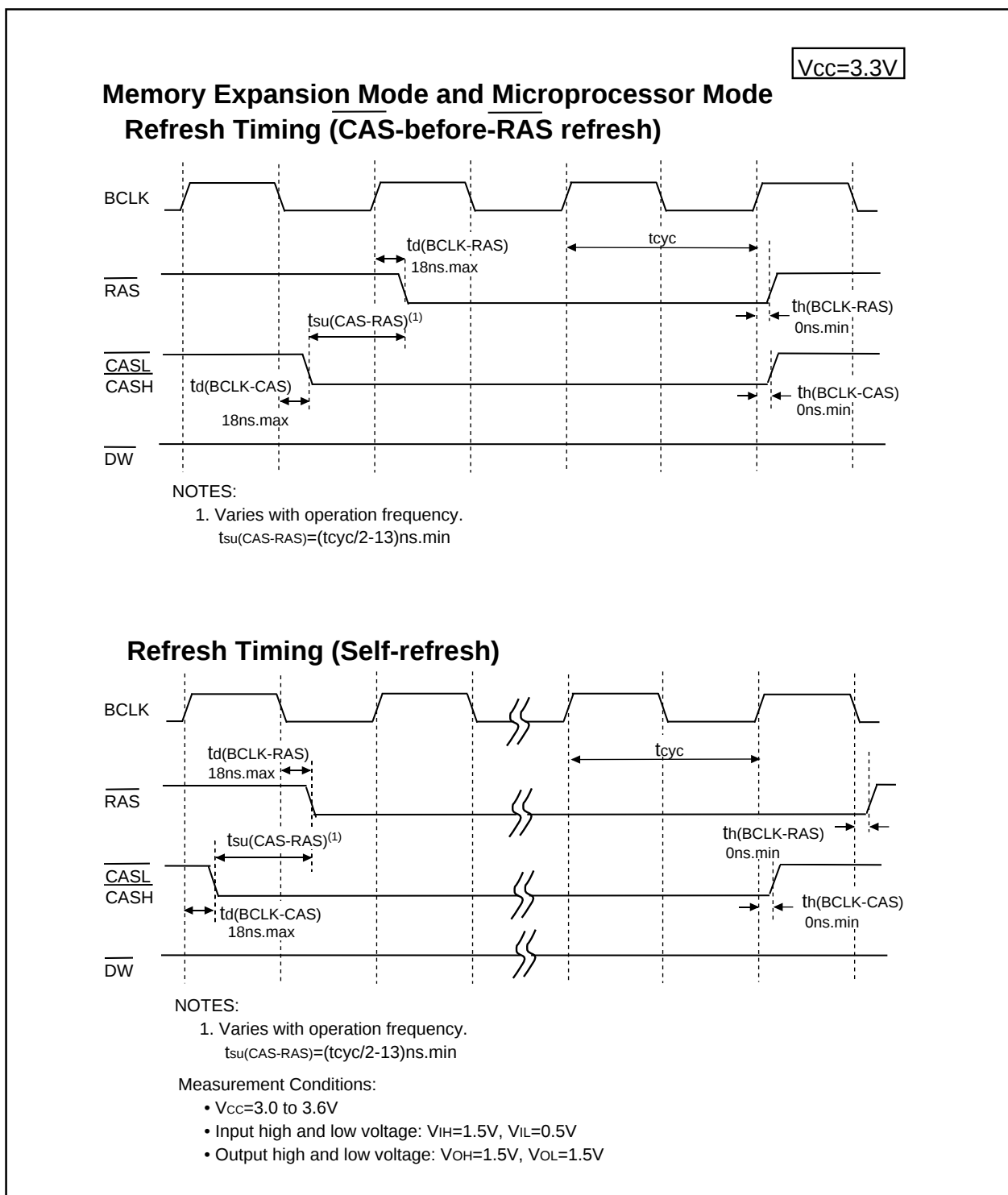
Figure 5.15 V_{CC}=3.3V Timing Diagram (6)

Table 5.46 Recommended Operating Conditions**(V_{CC}=4.2 to 5.5V, V_{SS}=0V at T_{opr} = -40 to 85°C (T version) unless otherwise specified)**

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
V _{CC}	Supply Voltage		4.2	5.0	5.5	V
AV _{CC}	Analog Supply Voltage			V _{CC}		V
V _{SS}	Supply Voltage			0		V
AV _{SS}	Analog Supply Voltage			0		V
V _{IH}	Input High ("H") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P87 ⁽³⁾ , P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	0.8V _{CC}		V _{CC}	V
		P70, P71	0.8V _{CC}		6.0	
V _{IL}	Input Low ("L") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87 ⁽³⁾ , P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	0		0.2V _{CC}	V
I _{OH(peak)}	Peak Output High ("H") Current ⁽²⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			-10.0	mA
I _{OH(avg)}	Average Output High ("H") Current ⁽¹⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			-5.0	mA
I _{OL(peak)}	Peak Output Low ("L") Current ⁽²⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			10.0	mA
I _{OL(avg)}	Average Output Low ("L") Current ⁽¹⁾	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽⁴⁾			5.0	mA
f(X _{IN})	Main Clock Input Frequency	V _{CC} =4.2 to 5.5V	0		32	MHz
f(X _{CIN})	Sub Clock Oscillation Frequency			32.768	50	kHz

NOTES:

- Typical values when average output current is 100ms.
- Total I_{OL(peak)} for P0, P1, P2, P86, P87, P9, P10, P11, P14 and P15 must be 80mA or less.
Total I_{OH(peak)} for P0, P1, P2, P86, P87, P9, P10, P11, P14 and P15 must be -80mA or less.
Total I_{OL(peak)} for P3, P4, P5, P6, P7, P80 to P84, P12 and P13 must be 80mA or less.
Total I_{OH(peak)} for P3, P4, P5, P6, P72 to P77, P80 to P84, P12 and P13 must be -80mA or less.
- V_{IH} and V_{IL} reference for P87 applies when P87 is used as a programmable input port.
It does not apply when P87 is used as X_{CIN}.
- P11 to P15 are provided in the 144-pin package only.

Timing Requirements(V_{CC} = 4.2 to 5.5V, V_{SS} = 0V at Topr = –40 to 85°C (T version) unless otherwise specified)**Table 5.52 Timer A Input (Count Source Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAin Input Cycle Time	100		ns
tw(TAH)	TAin Input High ("H") Pulse Width	40		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	40		ns

Table 5.53 Timer A Input (Gate Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAin Input Cycle Time	400		ns
tw(TAH)	TAin Input High ("H") Pulse Width	200		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	200		ns

Table 5.54 Timer A Input (External Trigger Input in One-Shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(TA)	TAin Input Cycle Time	200		ns
tw(TAH)	TAin Input High ("H") Pulse Width	100		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	100		ns

Table 5.55 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tw(TAH)	TAin Input High ("H") Pulse Width	100		ns
tw(TAL)	TAin Input Low ("L") Pulse Width	100		ns

Table 5.56 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min	Max	
tc(UP)	TAiout Input Cycle Time	2000		ns
tw(UPH)	TAiout Input High ("H") Pulse Width	1000		ns
tw(UPL)	TAiout Input Low ("L") Pulse Width	1000		ns
tsu(UP-TIN)	TAiout Input Setup Time	400		ns
th(TIN-UP)	TAiout Input Hold Time	400		ns

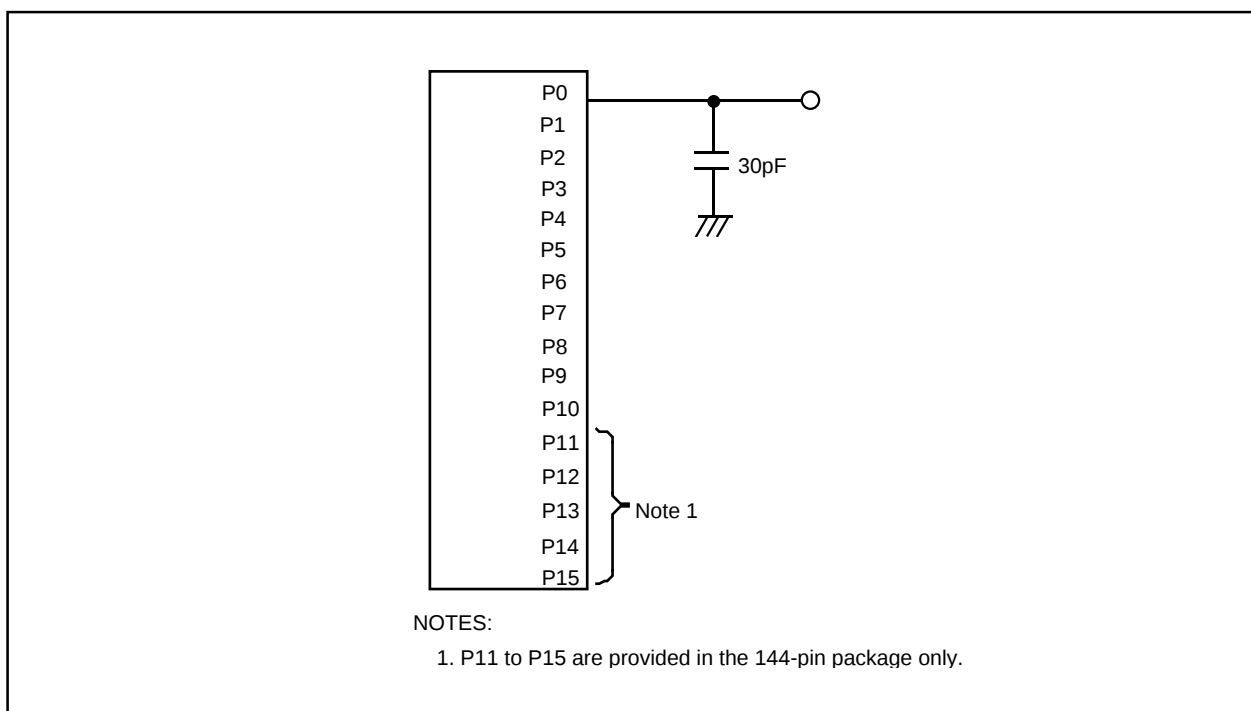


Figure 5.18 P0 to P15 Measurement Circuit

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